

## Single-Stage Primary-Regulation Controller for PFC and LED Dimmable Driving

### FEATURES

#### Wonderful Compatibility and Performance

- Compatible with TRIAC Dimming
- Primary Side Regulation (PSR)
- Constant Current output (+/- 1.5%)
- Universal Input Voltage Range

#### Energy Efficient

- Boundary Conduction Mode (BCM) with Valley Switching reduces EMI and enhances Efficiency
- Power Factor Correction (PF>95%)
- High Efficiency (>85% achievable)
- Low Startup Current: 1.5μA
- Low Operating Current: 1.9mA
- Low Quiescent Current: 1.2mA

#### Advanced Protection and Safety Features

- Open-LED Protection
- Short-LED Protection
- Cycle-by-Cycle Current Limit
- Over-Temperature Protection

#### Package

- SOP-8 Package Available

### DESCRIPTION

The primary-side-control offline LED lighting controller, SE8320, provides accurate output current, high power factor and low total harmonic distortion. High efficiency is achieved by low operating current and valley turn-on of the primary MOSFET. Constant on-time control is utilized for a better PFC performance.

TRIAC dimming is smoothly managed without flicker. Either primary side regulation or secondary side regulation, dimming model or no dimming model can be adopted by different set of DIM and FB pins.

The multi-protection of SE8320, including open-LED protection, short-LED protection, cycle-to-cycle current limit, VCC UVLO and over-temperature protection, can greatly enhance the system reliability. Current-limit threshold is adjusted automatically in a short-LED condition in order that the output current is minimized.

### APPLICATIONS

- Isolated LED Driver with/without TRIAC dimming
- Non-isolated LED Driver with/without TRIAC dimming
- Secondary Side Regulation LED Driver with/without TRIAC dimming

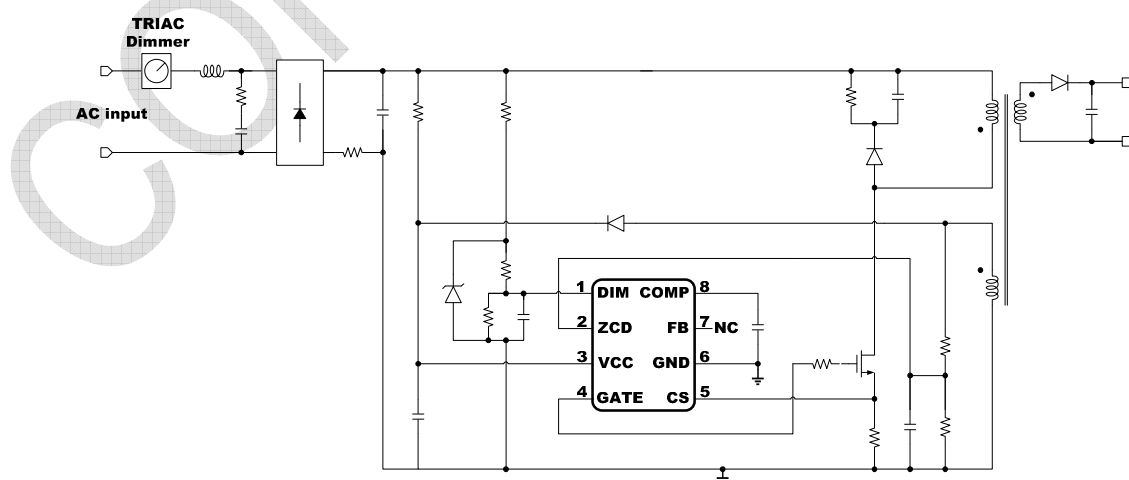


Figure 1. Typical Application

## FUNCTIONAL BLOCK DIAGRAM

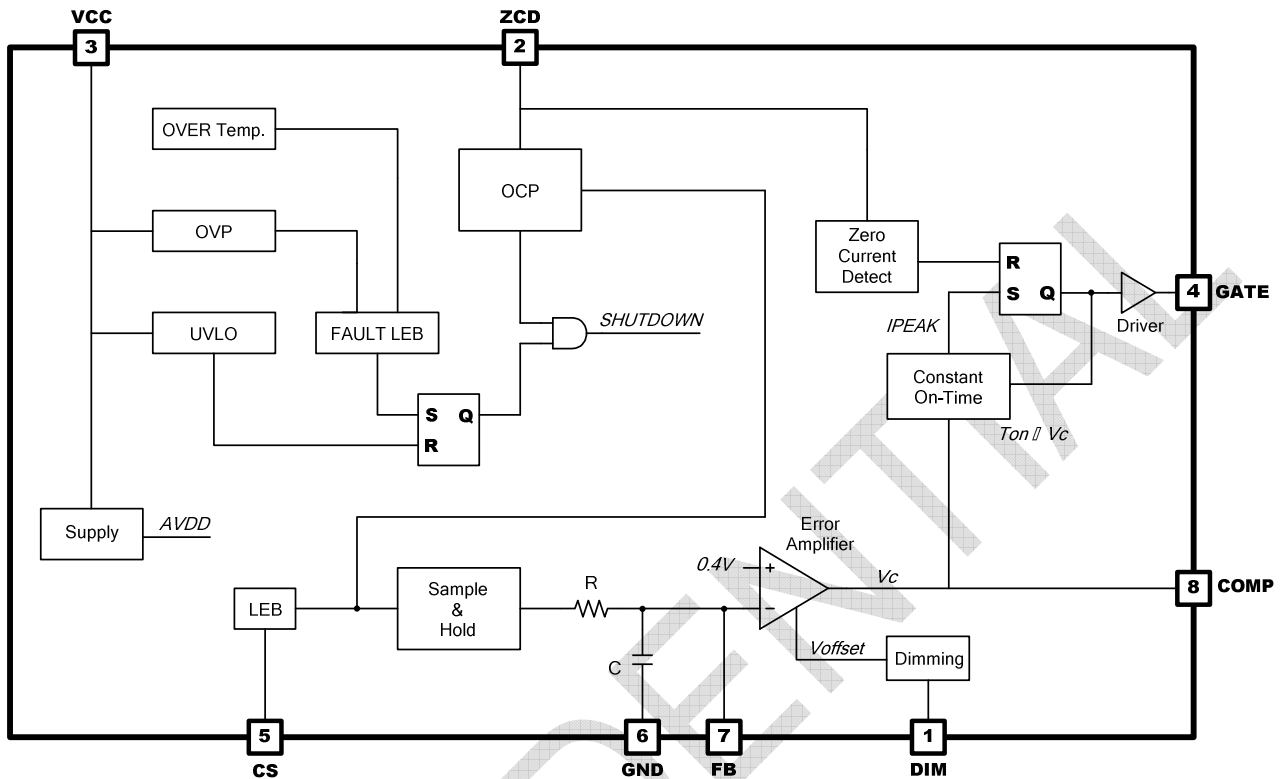


Figure 2. Functional Block Diagram

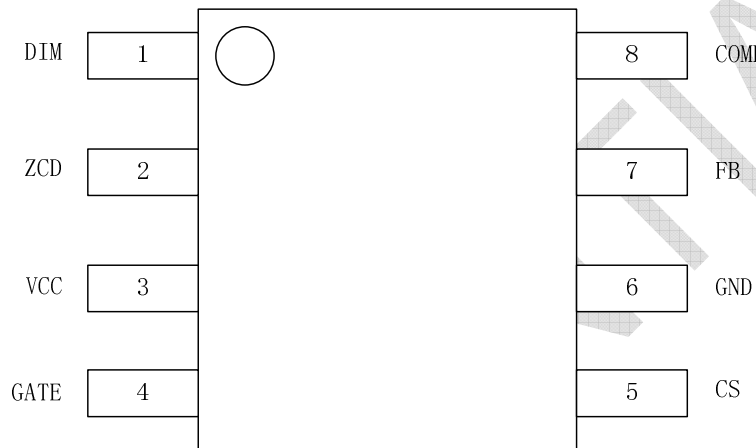
## PIN FUNCTIONS

Pin #	Name	Description
1	DIM	Dimming pin. This pin detects the TRIAC dimming phase to control the LED lighting. This pin can be NC if TRIAC dimming is not wanted.
2	ZCD	Zero current detection pin. Connect this pin through a resistor divider from the auxiliary winding to GND in order to detect the inductor current zero crossing point. This pin also detects the output voltage for OCP.
3	VCC	Power supply pin. This pin supply power both for IC operating current and GATE driving current.
4	GATE	Gate drive output pin. The totem pole output stage is able to drive high power MOSFET.
5	CS	Current sense pin. The MOSFET current is sensed via a resistor for constant current regulation and cycle-to-cycle current limit.
6	GND	Ground.
7	FB	Feedback Pin. This pin can be NC if primary side regulation is utilized.
8	COMP	Loop Compensation pin. Connect a compensation network to stabilize the loop.

## ORDERING INFORMATION

ORDERING NUMBER	PINS	PACKAGE
SE8320-SO-L	8	SOP

## PACKAGE REFERENCE



## ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit
Power Supply Voltage	$V_{CC}$	<30	V
ZCD Pin Input Voltage	$V_{ZCD}$	-0.3 to 7.0	V
CS Pin Input Voltage	$V_{CS}$	-0.3 to 7.0	V
DIM Pin Input Voltage	$V_{DIM}$	-0.3 to 7.0	V
COMP Pin Input Voltage	$V_{COMP}$	-0.3 to 7.0	V
GATE Pin Input Voltage	$V_{GATE}$	-0.3 to 30.0	V
Maximum Junction Temperature	$T_J$	<150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C
Lead Temperature (Soldering, 10s)	$T_{Lead}$	<260	°C

## ELECTRICAL CHARACTERISTICS

$V_{CC}=20V$ ,  $T_A=+27^{\circ}C$ , unless otherwise noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>SUPPLY SECTION</b> ( $T_A = -40^{\circ}C$ to $125^{\circ}C$ )						
$V_{CC}$	Operating Range		9		24	V
$V_{CC-ON}$	Turn-On Threshold Voltage		14	16	18	V
$V_{CC-OFF}$	Turn-Off Threshold Voltage		7	8	9	V
$V_{CC-HYS}$	$V_{CC}$ Hysteretic Voltage		7	8	9	V
$I_{CC}$	Operating Current	Switch Period = $15\mu s$	1.6	1.9	2.4	mA
$I_Q$	Quiescent Current	No switch	1	1.2	1.55	mA
$I_{ST}$	Startup Current	$V_{CC} = V_{CC-ON} - 0.16V$	1.4	1.5	1.6	$\mu A$
$V_{OVP}$	$V_{CC}$ Over-Voltage-Protection		24	25	25.5	V
$V_{OVP-HYS}$	OVP Hysteresis		0.9	1	1.05	V
<b>CONSTANT ON-TIME SECTION</b> ( $T_A = -40^{\circ}C$ to $125^{\circ}C$ )						
$T_{ON-MIN}$	Minimum On Time		0.7	1	1.5	$\mu s$
$T_{ON-MAX}$	Maximum On Time		20	24	27	$\mu s$
<b>ERROR AMPLIFIER SECTION</b>						
$G_M$	Transconductance			120		$\mu A/V$
$A_{EA}$	Voltage Gain			9000		V/V
$V_{FB}$	Feedback Voltage	$-40^{\circ}C < T_A < 125^{\circ}C$	0.384	0.398	0.405	V
$V_{COMP}$	COMP Voltage Range		0.9		4	V
$I_{C-SOURCE}$	Max Source Current		35	48	65	$\mu A$
$I_{C-SINK}$	Max Sink Current		-220	-294	-362	$\mu A$
<b>GATE DRIVER SECTION</b> ( $T_A = -40^{\circ}C$ to $125^{\circ}C$ )						
$V_{CLAMP}$	Output Clamp Voltage		11	12	14	V
$I_{G-SOURCE}$	Max Source Current		0.97	1.2	1.4	A
$I_{G-SINK}$	Max Sink Current		-1.2	-1.7	-2.1	A
<b>ZERO CURRENT DETECTOR SECTION</b>						
$V_{ZCD}$	ZCD Threshold			0.4		V
$V_{ZCD-HYS}$	ZCD Hysteresis			0.5		V
$T_{OFF-MIN}$	Minimum Off Time			3.6		$\mu s$
<b>AUTO START SECTION</b>						
$T_{START}$	Auto Start Time	$-40^{\circ}C < T_A < 125^{\circ}C$	100	140	190	$\mu s$

Continued on the following page...

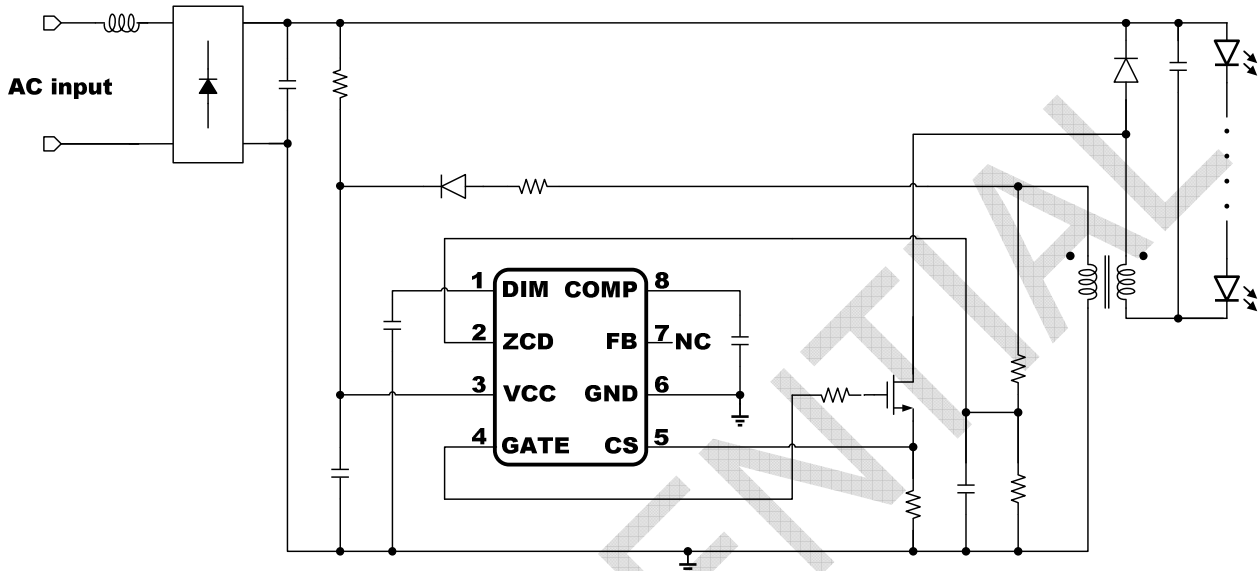
## ELECTRICAL CHARACTERISTICS

$V_{CC}=20V$ ,  $T_A=+27^{\circ}C$ , unless otherwise noted.

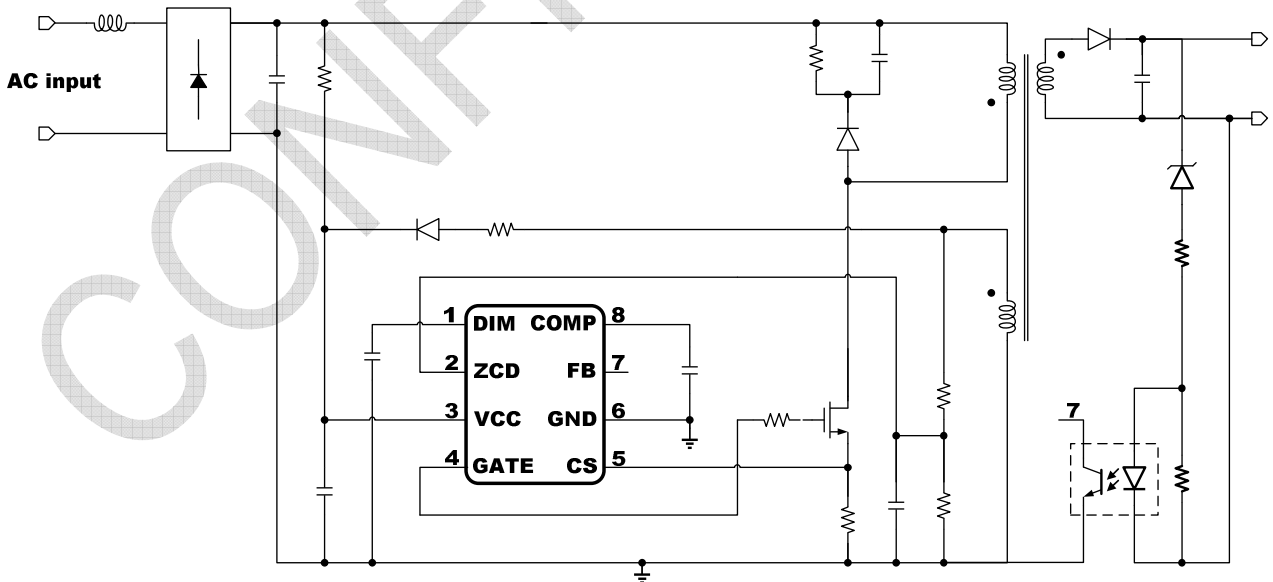
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>OVER-CURRENT PROTECTION SECTION</b>						
$V_{OCP-H}$	CS High Threshold Voltage for OCP			3		V
$V_{OCP-L}$	CS Low Threshold Voltage for OCP			1		V
$V_{HOCP-EN}$	ZCD Threshold Voltage to Enable High OCP level			0.9		V
$V_{LOCP-EN}$	ZCD Threshold Voltage to Enable Low OCP level			0.6		V
$T_{LEB}$	CS Sampling Leading-Edge Blanking Time			215		ns
<b>OVER TEMPERATURE PROTECTION SECTION</b>						
$T_{OTP}$	Over Temperature Protection		140	150	160	$^{\circ}C$
$T_{OTP-HYS}$	OTP Hysteresis		22	25	28	$^{\circ}C$
<b>DIMMING SECTION</b>						
$V_{DH}$	Maximum $V_{DIM}$ at Low Dimming Angle Range			3.5		V
$V_{DL}$	Maximum $V_{DIM}$ at High Dimming Angle Range			2.5		V
$DS_{DH}$	$V_{DIM}$ vs. $V_{FB-OFFSET}$ Slope at High Dimming Angle Range			0.23		V/V
$DS_{DL}$	$V_{DIM}$ vs. $V_{FB-OFFSET}$ Slope at Low Dimming Angle Range			0.08		V/V

## APPLICATION SCHEMATICS

### Non-Isolated Application



### Secondary Side Regulation Application





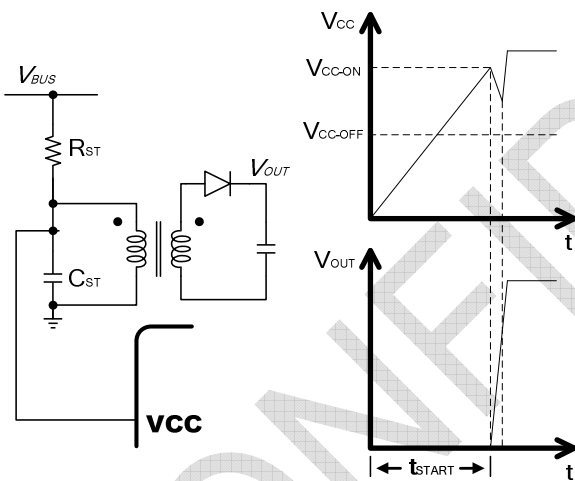
**SMET**

## FUNCTIONAL DESCRIPTION

SE8320 is a TRIAC dimmable single stage Flyback and PFC controller for LED lighting applications. Primary side control is applied so that the system is simplified, and high power factor is achieved by constant on-time model. Boundary Conduction Mode (BCM) with valley switching improves efficiency and EMI performance. The multi-protection function stabilizes system and protects external components.

### Startup

The capacitor  $C_{ST}$  across  $V_{BUS}$  and GND is charged by BUS through a start up resistor  $R_{ST}$  once BUS is powered on. After  $V_{CC}$  rises up to  $V_{CC-ON}$ , the internal blocks start to work and the gate driver begins to switch. Then  $V_{CC}$  will be pulled down by internal consumption until the power supply is taken over by the auxiliary winding.



**Figure 3. Startup Sequence**

In order that  $V_{CC}$  can rise when start up, and fall when OVP and OTP,  $R_{ST}$  should be preset following this:

Select  $C_{ST}$  for an ideal  $t_{ST}$ :

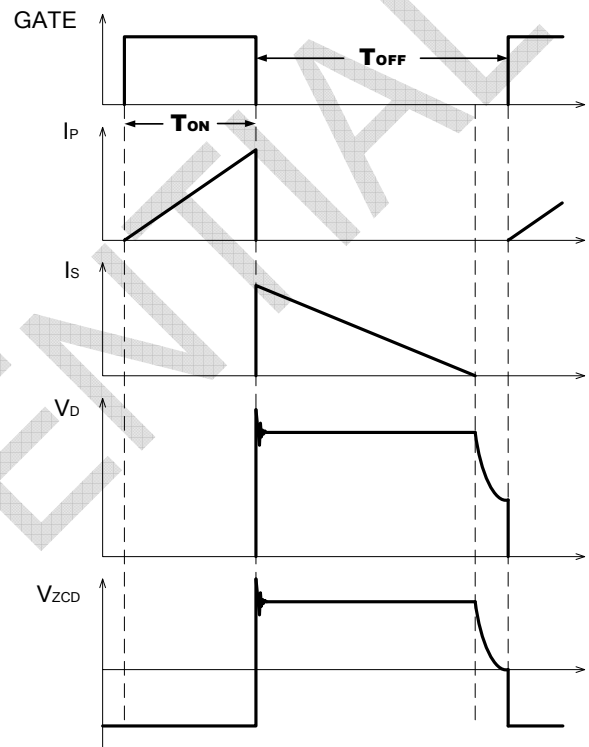
$$t_{ST} = \frac{R_{ST} \cdot C_{ST}}{1}$$

# SE8320

For a more stable  $V_{CC}$ , a bigger  $C_{ST}$  is needed, and  $R_{ST}$  should be decreased in order that  $t_{ST}$  is not changed. Obviously, the low  $I_{ST}$  of SE8320 makes it easier to design  $R_{ST}$ .

### Boundary Conduction Mode Operation

Boundary Conduction Mode (BCM) and valley switching provides low turn-on switching losses.



**Figure 4. Boundary Conduction Mode**

The voltage across drain and source of the external MOSFET is detected by the ZCD pin. The current of the inductor begins to decrease linearly as soon as the external MOSFET is turned off. When the current falls to zero, the MOSFET Drain-Source Voltage decreases, which is also detected by the ZCD pin through a resistor divider. The external MOSFET would be turned on by a turn on signal sent by the Zero Current Detector once the ZCD voltage is lower than 0.4V.

### Primary Side Constant Current Control

The output mean current can be represented as

$$I_{OUT} = \frac{V_{BUS}}{R_{ST}}$$



$V_{FB}$ —The feedback reference voltage, typically 0.4V.

N—The winding turns ratio of primary side to secondary side of the transformer.

$R_{CS}$ —The current sense resistor connected between the CS pin and GND.

CONFIDENTIAL



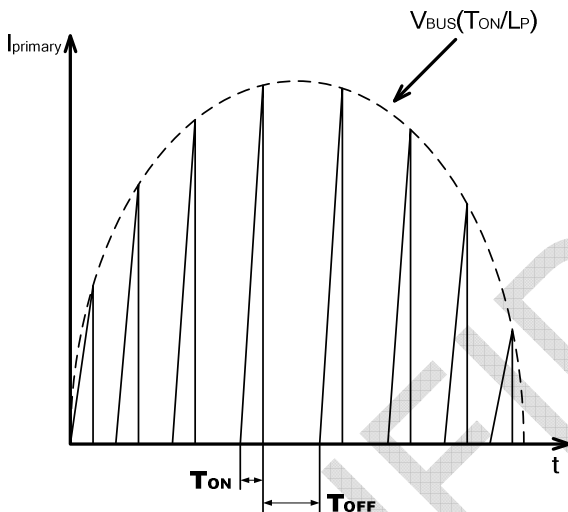
## FUNCTIONAL DESCRIPTION

### Power Factor Correction

Internal Constant On-Time Block affords a constant gate on-time  $T_{ON}$ , which is in proportion to COMP potential. The peak current of the primary side winding is

$$I_P = \frac{V_{BUS}}{L_P}$$

$L_P$ —The primary inductance.  
As  $L_P$  and  $T_{ON}$  is constant,  $I_P$  is accordingly in proportion to  $V_{BUS}$  (as shown in Figure 5).



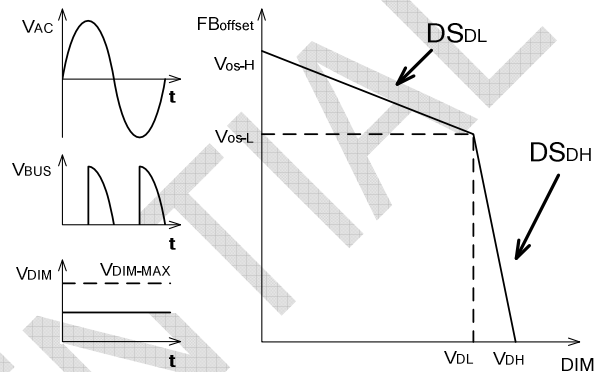
**Figure 5. Power Factor Correction**

As a result, the input current  $I_{IN}$  of the system follows the input voltage  $V_{IN}$ , and the Power Factor is improved.

### TRIAC Dimming Control

SE8320 can implement TRIAC dimming function by internal dimming block and external passive components. The Zener diode clamp voltage is divided by two resistors, as shown in Figure 1, to obtain  $V_{DIM-MAX}$  in Figure 6. Dimming angle  $\theta_{DIM}$  is sensed by the Zener diode and consequently changes  $V_{DIM}$ .

When  $V_{DIM}$  is lower than  $V_{DH}$ ,  $FB_{offset}$  increases as  $V_{DIM}$  decreases. This offset voltage eventually reduces the LED brightness. The external dimming components can be replaced by a 1nF capacitor to GND to disable the dimming function. An internal current source would charge this capacitor to over  $V_{DH}$ .



**Figure 6. Dimming Function**

### VCC Under-Voltage Lockout (UVLO)

When the  $V_{CC}$  voltage drops below  $V_{CC-OFF}$  (typically 8V), the whole chip shuts down, and GATE switching stops. The system would not work again until  $V_{CC}$  capacitor is charged to  $V_{CC-ON}$  through the external startup resistor.

### Auto Start

An auto start block is integrated in SE8320 to avoid unnecessary shut down. The auto start block starts timing as soon as the external MOSFET turns on in every period. If the ZCD pin fails to send a turn on signal after  $T_{START}$  (typically 140 $\mu$ s), the auto start block would turn on GATE automatically.

When the GATE is turned on, auto start timing stops.

### Minimum Off Time

To limit the maximum switching frequency and to obtain a better EMI performance, an internal block is integrated to limit the minimum GATE off time. The external MOSFET cannot turn on again in less than 3.6 $\mu$ s after its latest turning off.

### Leading Edge Blanking (LEB)

An internal leading edge blanking (LEB) block is employed in order to avoid the premature termination of the GATE switching pulse due to



the peak voltage of the CS pin caused by the parasitic capacitor discharging when the external

MOSFET turns on.  $V_{CS}$  sampling is disabled during the LEB time.

CONFIDENTIAL

## FUNCTIONAL DESCRIPTION

### Open-LED Protection

When the load of the system is open, the output capacitor is charged up rapidly. Consequently,  $V_{CC}$  rises up quickly since the VCC capacitor is charged by the auxiliary winding and its voltage reflects the output voltage.

The whole chip enters fault state, in which GATE will never be turned on, as soon as the voltage of the VCC pin rises up to  $V_{OVP}$  (typically 25V). As the external MOSFET is always off in the fault state, the auxiliary winding cannot support the  $V_{CC}$  consumption, and  $V_{CC}$  will drop. This fault state will last until UVLO.

### Short-LED Protection

The voltage of the ZCD pin reflects the output voltage when the switch is on. The short-LED situation can be detected through the ZCD pin and the OCP threshold would be changed in that case.

If the ZCD voltage in GATE on period is lower than 0.6V, the cycle-by-cycle current limit would be 1V. The current limit threshold voltage becomes up to 3V when the ZCD voltage in GATE on period is higher than 0.9V. Figure 7 shows this function.

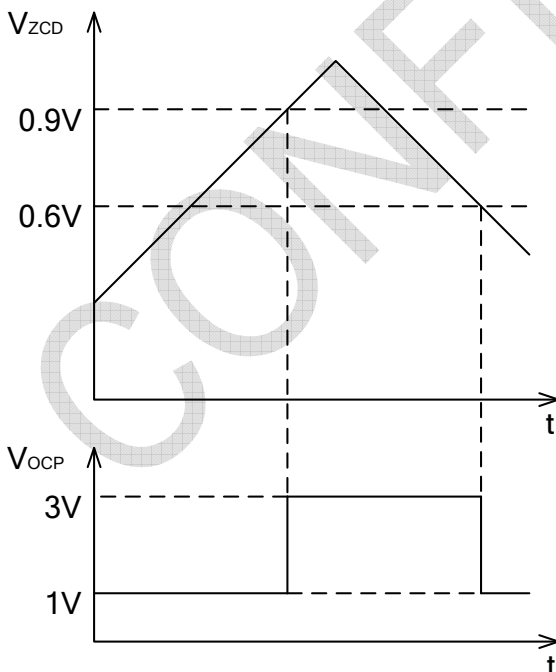


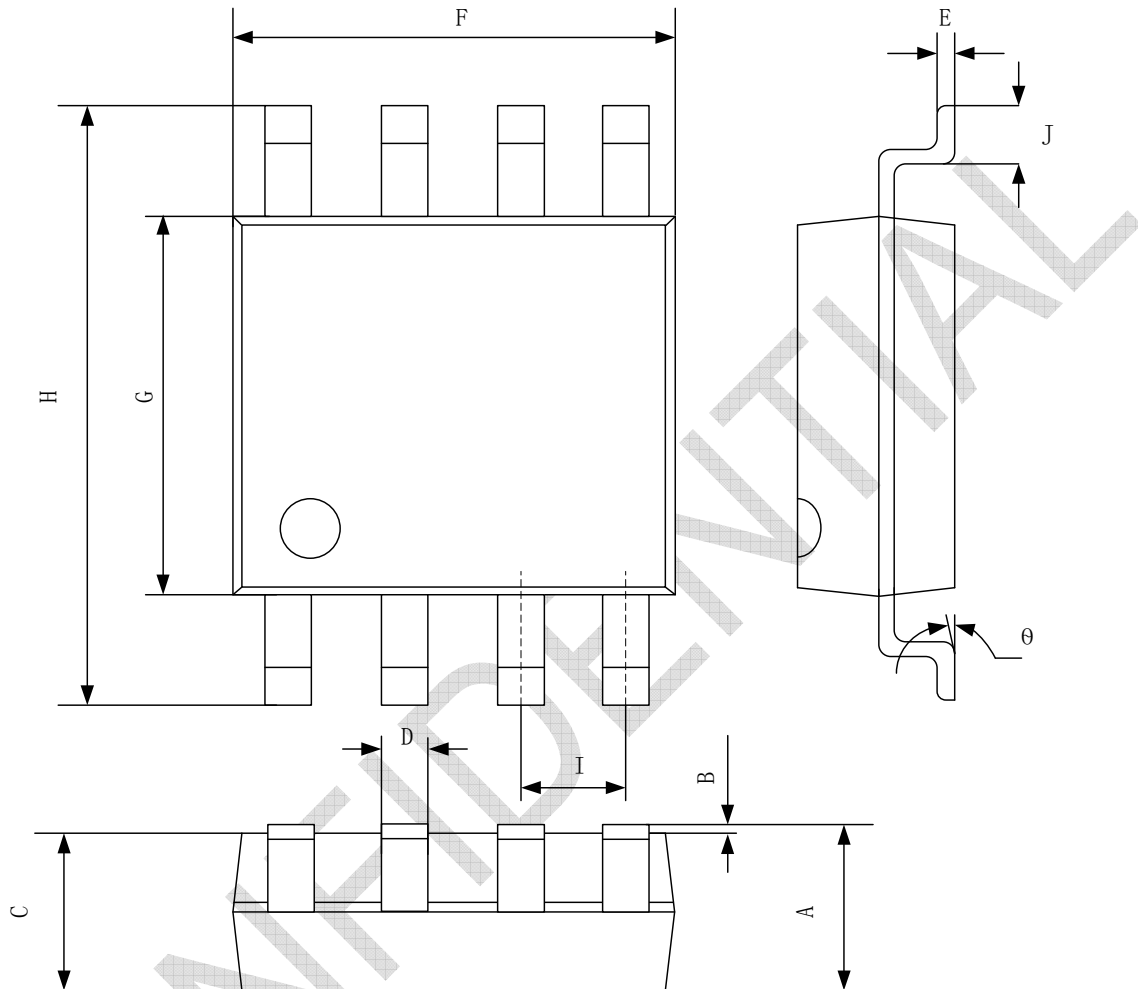
Figure 6. OCP Function

A lower OCP voltage can protect the external MOSFET as well as reduce power dissipation. As output voltage is low in the short-LED condition, the auxiliary winding cannot charge the VCC capacitor, and  $V_{CC}$  will consequently drop until UVLO.

### Over-Temperature Protection (OTP)

When the junction temperature is above 150°C, the chip enters fault state, and GATE driver is shut down. The UVLO signal can relieve the system of fault state if the junction temperature drops below 125°C.

## PACKAGE INFORMATION



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
B	0.100	0.250	0.004	0.010
C	1.350	1.550	0.053	0.061
D	0.330	0.510	0.013	0.020
E	0.170	0.250	0.006	0.010
F	4.700	5.100	0.185	0.200
G	3.800	4.000	0.150	0.157
H	5.800	6.200	0.228	0.244
I	1.270(BSC)		0.050(BSC)	
J	0.400	1.270	0.400	1.270
θ	0°		8°	

## **SOLDERING INDICATION**

This section gives a very brief insight to a complex technology. There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

### **Reflow Soldering**

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stenciling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250°C. The top-surface temperature of the packages should preferably be kept below 220°C for thick/large packages, and below 235°C for small/thin packages.

### **Wave Soldering**

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used, the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch:
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is preferred to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis must be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250°C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

## Manual Soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300°C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320°C.

## Suitability of Surface Mount IC Packages for Wave and Reflow Soldering Methods

Package	Soldering Method	
	Wave	Reflow <sup>(1)</sup>
BGA, HBGA, LFBGA, SQFP, TFBGA	Not suitable <sup>(2)</sup>	Suitable
HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, SMS	Not suitable	Suitable
PLCC (3), SO, SOJ	Suitable	Suitable
LQFP, QFP, TQFP	Not recommended <sup>(3)(4)</sup>	Suitable
SSOP, TSSOP, VSO	Not recommended <sup>(5)</sup>	Suitable

### Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect).
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch equal to or smaller than 0.5 mm.



Star Micro Electronic Technology Co.Ltd  
Room 602 UESTC Industrial Building  
NO.159, 1st Ring Rd, Chengdu, China  
Tel: (86) 28 8113 1361  
Fax: (86) 28 8113 1841  
Email: sales@star-micro.com  
Website: www.star-micro.com

**IMPORTANT NOTICE**

"Preliminary" product information describes products that are in production, but for which full characterization data is not yet available. SMET Ltd. believes that the information contained in this document is accurate and reliable. However, the information is subject to change without notice and is provided "AS IS" without warranty of any kind (express or implied). Customers are advised to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability. No responsibility is assumed by SMET for the use of this information, including use of this information as the basis for manufacture or sale of any items, or for infringement of patents or other rights of third parties. This document is the property of SMET and by furnishing this information, SMET grants no license, express or implied under any patents, mask work rights, copyrights, trademarks, trade secrets or other intellectual property rights. SMET owns the copyrights associated with the information contained herein and gives consent for copies to be made of the information only for use within your organization with respect to SMET integrated circuits or other products of SMET. This consent does not extend to other copying such as copying for general distribution, advertising or promotional purposes, or for creating any work for resale. An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technologies described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan. An export license and /or quota needs to be obtained from the competent authorities of the Chinese Government if any of the products or technologies described in this material is subject to the PRC Foreign Trade Law and is to be exported or taken out of the PRC. CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). SMET PRODUCTS ARE NOT DESIGNED, AUTHORIZED OR WARRANTED FOR USE IN AIRCRAFT SYSTEMS, MILITARY APPLICATIONS, PRODUCTS SURGICALLY IMPLANTED INTO THE BODY, LIFE SUPPORT PRODUCTS OR OTHER CRITICAL APPLICATIONS (INCLUDING MEDICAL DEVICES, AIRCRAFT SYSTEMS OR COMPONENTS AND PERSONAL OR AUTOMOTIVE SAFETY OR SECURITY DEVICES). INCLUSION OF SMET PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK AND SMET DISCLAIMS AND MAKES NO WARRANTY, EXPRESS, STATUTORY OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR PARTICULAR PURPOSE, WITH REGARD TO ANY SMET PRODUCT THAT IS USED IN SUCH A MANNER. IF THE CUSTOMER OR CUSTOMER'S CUSTOMER USES OR PERMITS THE USE OF SMET PRODUCTS IN CRITICAL APPLICATIONS, CUSTOMER AGREES, BY SUCH USE, TO FULLY INDEMNIFY SMET, ITS OFFICERS, DIRECTORS, EMPLOYEES, DISTRIBUTORS AND OTHER AGENTS FROM ANY AND ALL LIABILITY, INCLUDING ATTORNEYS' FEES AND COSTS, THAT MAY RESULT FROM OR ARISE IN CONNECTION WITH THESE USES.